0.10 С

0.10 C

△ 0.08 C

28X ∅ b

C A B

С 0.03

0.05

0

NOTE 3

TOP VIEW DETAIL A

SIDE VIEW

e/2

F

Е

D

С

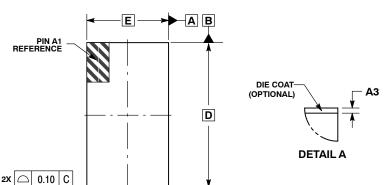
В Α

> 2 3 **BOTTOM VIEW**



WLCSP28, 2.9x1.9, 0.4P CASE 567JJ ISSUE D

DATE 18 NOV 2014



е

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS		
DIM	MIN	MAX	
Α		0.60	
A1	0.17	0.23	
A2	0.36 REF		
АЗ	0.02	0.03	
b	0.24	0.30	
D	2.90 BSC		
Е	1.90 BSC		
е	0.40 BSC		

GENERIC MARKING DIAGRAM*



= Assembly Location

= Wafer Lot

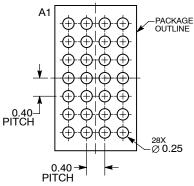
= Year

WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

RECOMMENDED **SOLDERING FOOTPRINT***



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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